

IN THE CLAIMS

Please substitute claims 1-17 with the following:

1. (Currently Amended) A solid-state image pickup device comprising:

a circuit board having an opening;

a sensor package in which a chip of a solid-state image pickup element with a light-receiving surface is placed, the sensor package disposed at one surface of the circuit board so that the light-receiving surface of the chip of the solid-state image pickup element opposes the opening;

a seal adhered to the sensor package for sealing in the solid-state image pickup element;

and

an optical unit disposed at the other surface of the circuit board so that incident light is focused on the light-receiving surface,

wherein the circuit board is disposed between the sensor package and the optical unit, and

wherein the seal is placed within the opening of the circuit board.

2. (Original) A solid-state image pickup device according to Claim 1, wherein the sensor package includes a signal processing circuit for processing a signal of the solid-state image pickup element.

3. (Original) A solid-state image pickup device according to Claim 1, wherein the solid-state image pickup element has a signal processing function.

4. (Original) A solid-state image pickup device according to Claim 1, wherein the circuit board is connected to an external device without a connector.

5. (Currently Amended) A method of producing a solid-state image pickup device comprising the steps of:

providing a circuit board with an opening;

joining a sensor package, in which a chip of a solid-state image pickup element has been previously sealed, to one surface of the circuit board so that a light-receiving surface of the chip of the solid-state image pickup element opposes the opening ~~and so that a seal adhered to the sensor package is placed within the opening of the circuit board;~~ and

disposing and joining an optical unit at and to the other surface of the circuit board so that incident light is focused on the light-receiving surface,

wherein the circuit board is disposed between the sensor package and the optical unit.

6. (Original) A method of producing a solid-state image pickup device according to Claim 5, wherein the sensor package includes a signal processing circuit for processing a signal of the solid-state image pickup element.

7. (Original) A method of producing a solid-state image pickup device according to Claim 5, wherein the solid-state image pickup element has a signal processing function.

8. (Original) A method of producing a solid-state image pickup device according to Claim 5, wherein the circuit board is connected to an external device without a connector.

9. (Previously Presented) A solid-state image pickup device according to Claim 1, wherein the seal is a glass seal.

10. (New) A method of producing a solid-state image pickup device according to Claim 5, further comprising placing a seal adhered to the sensor package within the opening of the circuit board.

11. (New) A solid-state image pickup device comprising:
 - a circuit board having an opening;
 - a sensor package in which a chip of a solid-state image pickup element with a light-receiving surface is placed, the sensor package disposed at one surface of the circuit board so that the light-receiving surface of the chip of the solid-state image pickup element opposes the opening; and
 - an optical unit disposed at the other surface of the circuit board so that incident light is focused on the light-receiving surface,wherein the circuit board is disposed between the sensor package and the optical unit.
12. (New) A solid-state image pickup device according to Claim 11, wherein the sensor package includes a signal processing circuit for processing a signal of the solid-state image pickup element.
13. (New) A solid-state image pickup device according to Claim 11, wherein the solid-state image pickup element has a signal processing function.
14. (New) A solid-state image pickup device according to Claim 11, wherein the circuit board is connected to an external device without a connector.
15. (New) A solid-state image pickup device according to Claim 1, wherein the solid-state image pickup element is disposed on a surface of the sensor package.
16. (New) A method of producing a solid-state image pickup device according to Claim 5, wherein the solid-state image pickup element is disposed on a surface of the sensor package.

17. (New) A solid-state image pickup device according to Claim 11, wherein the solid-state image pickup element is disposed on a surface of the sensor package.